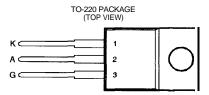
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- 8 A Continuous On-State Current
- 80 A Surge-Current
- Glass Passivated Wafer
- 400 V to 800 V Off-State Voltage
- Max IGT of 20 mA



Pin 2 is In electrical contact with the mounting base.

MDC1ACA

#### absolute maximum ratings over operating case temperature (unless otherwise noted)

RATING		SYMBOL	VALUE	UNIT
Repetitive peak off-state voltage (see Note 1)	TIC116D TIC116M TIC116S TIC116N	V <sub>DRM</sub>	400 600 700 600	v
Repetitive peak reverse vollage	V <sub>RRM</sub>	<b>400</b> 600 700 600	v	
Continuous on-state current at (or below) 60°C Case temperature (see Note 2)	I <sub>T(RMS)</sub>	8	A	
Average on-state current (180° conduction angle) at (or below) 80°C case temperature (see Note 3)			5	А
Surge on-state current (see Note 4)			60	А
Peak positive gate current (pulse width≤300 µs)	GM	3	A	
Peak gate power dissipation (pulse width ≤ 300 us)	Рдм	5	W	
Average gate power dissipation (see Note 5)	P <sub>G(AV)</sub>	1	W	
Operating case temperature range	Τc	-40 to +110	۰C	
Storage temperature range	T <sub>stg</sub>	-40 to +125	°C	
Lead temperature 1.6 mm from case for 10 seconds	ΤL	230	°C	

NOTES: 1. These values apply when the gate-cathode resistance  $R_{GK} = 1 k\Omega$ .

- 2. These values apply for continuous dc operation with resistive load. Above 60°C derate linearly to zero at 110°C.
- 3. This value may be applied continuously under single phase 50 Hz half-sine-wave operation with resistive load. Above 60°C derate linearly to zero at 110°C.

4. This value applies for one 50 Hz half-sine-wave when the device is operating at (or below) the rated value of peak reverse voltage and on-state current. Surge may be repeated after the device has returned to original thermal equilibrium.

5. This value applies for a maximum averaging time of 20 ms.





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#### dectrical characteristics at 25°C case temperature (unless otherwise noted)

PARAMETER			TEST CONDITIO	ONS	MIN	TYP	YP MAX	UNIT
IDRM	Repetitive peak off-state current	V <sub>D</sub> = rated V <sub>DRM</sub>	R <sub>GK</sub> = 1 kΩ	T <sub>C</sub> = 110°C			2	mA
IRRM	Repetitive peak reverse current	V <sub>R</sub> ≈ rated V <sub>RRM</sub>	l <sub>G</sub> = 0	T <sub>C</sub> = 110°C			2	mА
IGT	Gate trigger current	V <sub>AA</sub> = 6 V	$R_L = 100 \Omega$	t <sub>p(g)</sub> ≥ 20 μs		5	20	mA
V <sub>GT</sub>	Gate <b>trigger voltage</b>	V <sub>AA</sub> = 6 V t <sub>p(g)</sub> ≥ 20 µs	R <sub>L</sub> = 100 Ω R <sub>GK</sub> = 1 kΩ	$T_{\rm C} = -40^{\circ}{\rm C}$			2.5	
		V <sub>AA</sub> = 6 V t <sub>p(g)</sub> ≥ 20 µs	R <sub>L</sub> = 100 Ω R <sub>GK</sub> = 1 kΩ			0.8	1.5	v
		V <sub>AA</sub> = 6 V t <sub>p(g)</sub> ≥ 20 µs	R <sub>L</sub> = 100 Ω R <sub>GK</sub> = 1 kΩ	T <sub>C</sub> = 110°C	0.2			
ŀн	Holding current	V <sub>AA</sub> = 6 V Initiating I <sub>T</sub> = 100 mA	R <sub>GK</sub> = 1 kΩ	T <sub>C</sub> = - 40°C			70	
		V <sub>AA</sub> = 6 V Initiating I <sub>T</sub> = 100 mA	R <sub>GK</sub> = 1 kΩ				40	mA
V <sub>TM</sub>	Peak on-state voltage	I <sub>TM</sub> = 8 A	(see Note 6)				1.7	v
dv/dt	Critical rate of rise of off-state voltage	V <sub>D</sub> = rated V <sub>D</sub>	l <sub>G</sub> = 0	T <sub>C</sub> = 110°C		100		V/µs

NOTE 6: This parameter must be measured using pulse techniques, t<sub>p</sub> = 300 µs, duty cycle ≤ 2 %. Voltage sensing-contacts, separate from the current canying contacts, are located within 3.2 mm from the device body.

### thermal characteristics

	PARAMETER	YIN	ΤΥF	MAX	UNIT
R <sub>ØJC</sub>	Junction to case thermal resistance			3	°C/W
R <sub>eja</sub>	Junction to free air thermal resistance			62.	5 ° <b>C/W</b>

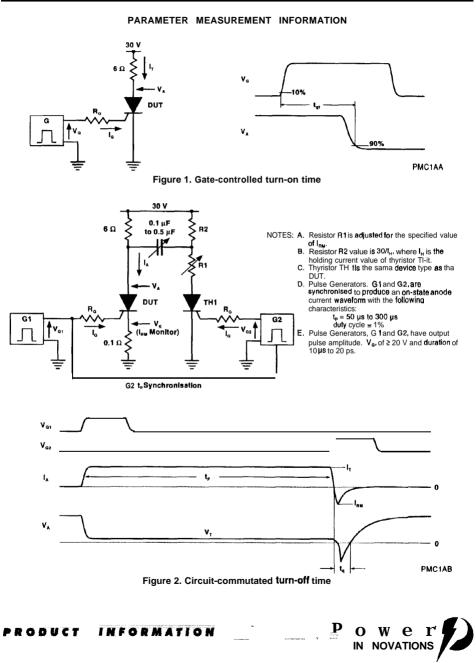
#### resistive-load-switching characteristics at 25°C case temperature

	PARAMETER	TEST CONDITIONS			MIN	ТҮР	MAX	UNIT
<sup>t</sup> gt	Gate-controlled turn-on <b>time</b>	l <sub>T</sub> = 5 A	<b>I</b> G = 200 mA	See Figure 1		0.6		μs
t <sub>a</sub>	Circult-commutated tum-off time	l <sub>7</sub> = 5 Α	l <sub>RM</sub> = 10 A	See Figure 2		11		μs

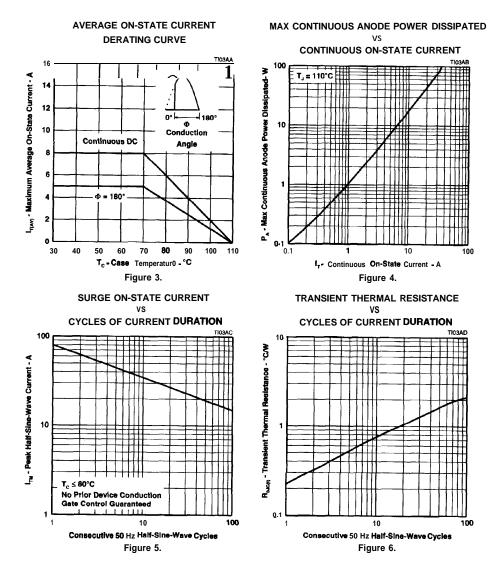
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# PRODUCT INFORMATION

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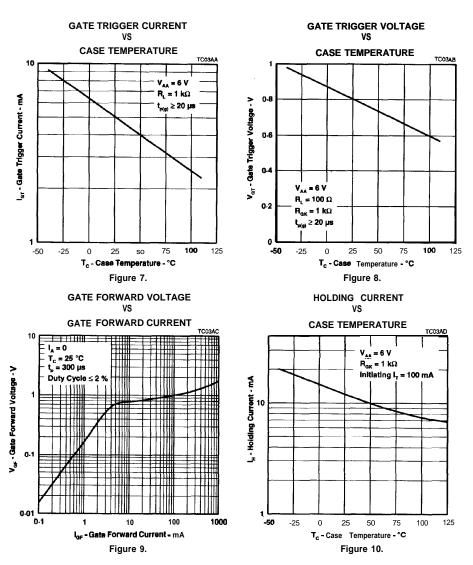


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# TYPICAL CHARACTERISTICS

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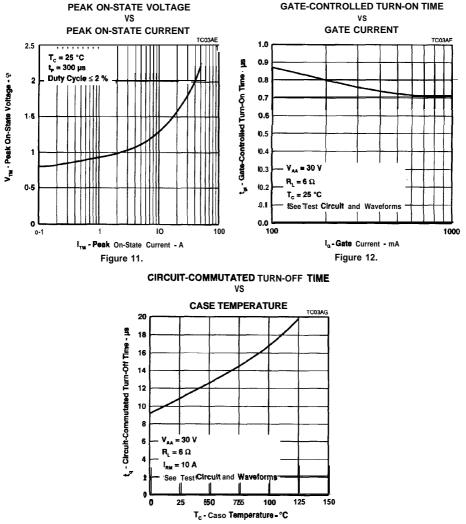


#### **TYPICAL CHARACTERISTICS**





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### **TYPICAL CHARACTERISTICS**

Figure 13.



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